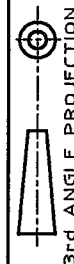




THE DATASHEET OF
1-178138-5



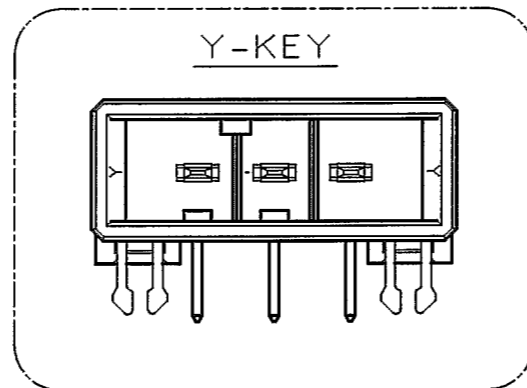
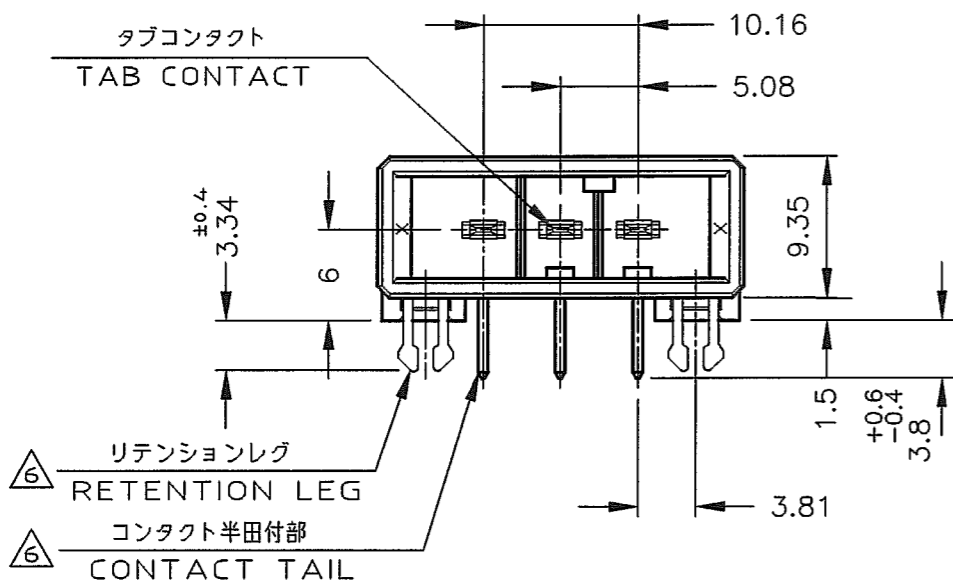
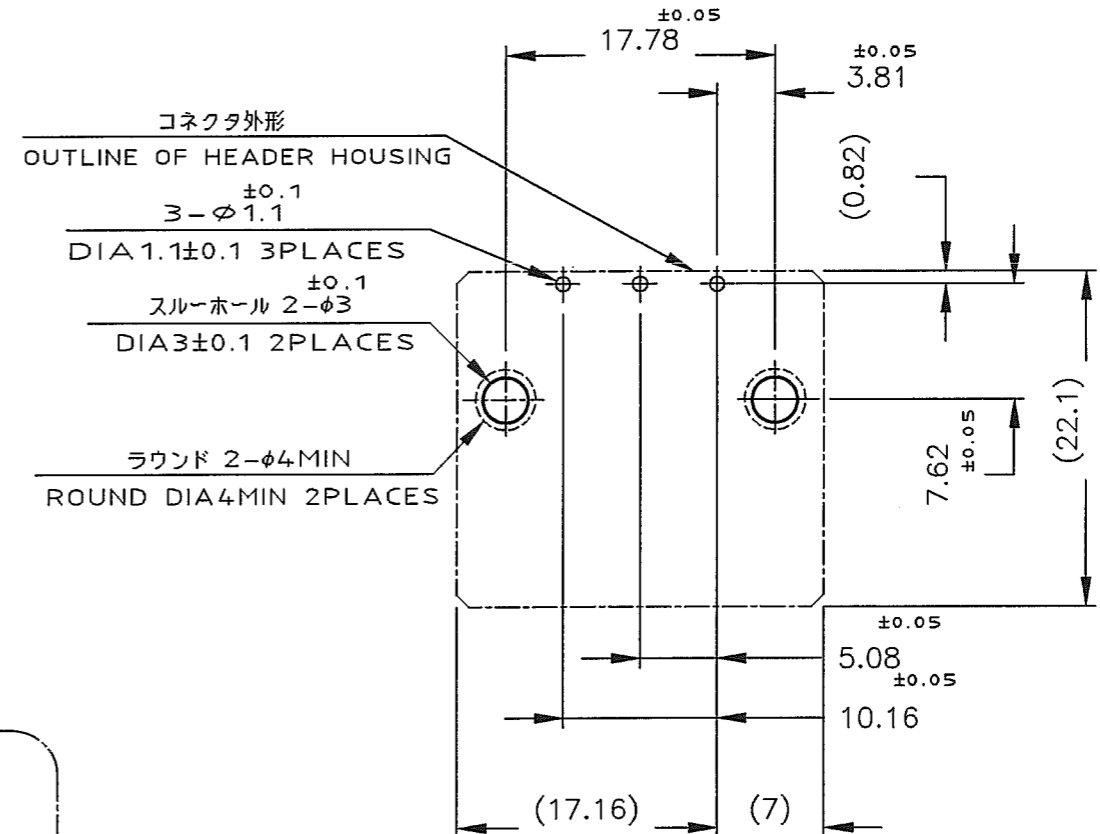
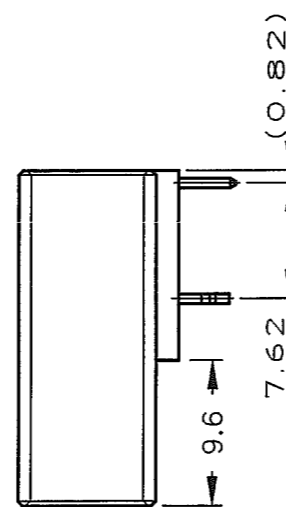
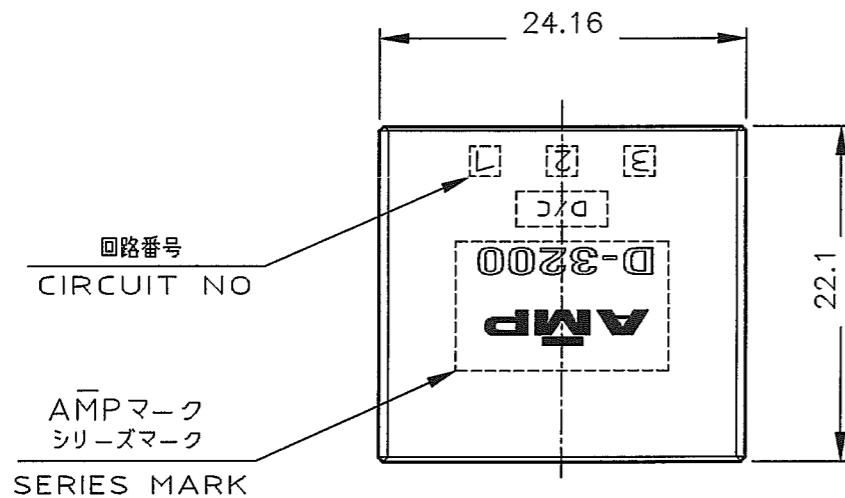
NUMBER 178138



METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST



推奨基板取付け穴寸法
PC 基板厚: 1.6 ± 0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS: 1.6 ± 0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

NOTES

- MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂
コンタクト: 銅合金
リテンションレグ: 銅合金
- めっき: コンタクト: 全面Ni下地
接触部: 0.38 μm MIN 金めっき
- めっき: コンタクト: 全面Ni下地
接触部: 0.76 μm MIN 金めっき
- めっき: コンタクト: 全面Ni下地
接触部: 2.0 μm MIN スズめっき
- めっき: リテンションレグとコンタクト半田付部
ニッケル下地の上に半田めっき
- めっき: リテンションレグとコンタクト半田付部
ニッケル下地の上にスズめっき

△6	△4	2-178138-5	Y
△6	△3	2-178138-3	Y
△6	△2	2-178138-2	Y
△6	△4	1-178138-5	X
△6	△3	1-178138-3	X
△6	△2	1-178138-2	X
(FINISH)		製品番号 (PART NO.)	KEY

WIRE RANGE		INSULATION DIA	NAME	
mm ² (AWG -)		mmφ	3 POS SINGLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200	
MATERIAL SEE NOTE 注記参照		FINISH SEE NOTE 注記参照		
DR.	20/MAR/95 K.IKEDA	DE.	20/MAR/95 K.IKEDA	一般公差 (GENERAL TOLERANCE) 100μF : ±0.3 1000μF 300V : ±0.4 3000μF 1000V : ±0.5 角 度 : ±3'
LTR	REVISION RECORD	DR	CHK	DATE
E1	REVISED PER ECO-11-005030	RK	HMR	23/MAR/11
SCALE 2-1		REV. E1	SHEET 1 OF 1	



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